

# **PRODUCT SPECIFICATION**

# 16X1 CHARACTERSLCD MODULE MODEL: C1601C7SGW6B-B0 Ver:1.6

<>> Preliminary Specification

<♦>Finally Specification

CUSTOMER'S APPROVAL						
CUSTOMER:						
SIGNATURE:	DATE:					
)						

PM	PD	PREPARED
REVIEWED	REVIEWED	BY
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		-

# **Revision Status**

Version	Revise Date	Page	Content	Modified By
Ver 1.0	2014-07-25		First Issued	
Ver 1.1	2014-08-19	21	Add Packing Instruction	
Ver 1.2	2014-11-24		Modify the PCB,Improve the BackLight	
Ver 1.3	2014-12-09		Modify the PCB,Improve the BackLight, Change the LCD;	
Ver 1.4	2015-10-28	5,20	Modify Vop;	
Ver 1.5	2015-12-15	5	Update ELECTRICAL SPEC.	
Ver 1.6	2017-09-18		Change IC	

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### 1. Features

The features of LCD are showed as follows

\* Display mode : STN /Transmissive/ Negative \* Controller IC : UCI7066-01(English-Japanese)

\* Display format : 16X1Characters \* Interface Input Data : 4 bit or 8 bit MPU \* Driving Method : 1/16Duty, 1/5Bias

\* Viewing Direction : 6 O'clock

\* Backlight : 1 LED/Side White

\*Sample NO. : C1601C7SGW6B-B0\_05/20170913

### 2. MECHANICAL SPECIFICATIONS

Item	Specification	Unit
Module Size	122(W) x44(H) x13.0(D)	mm
Viewing Area	99MIN(W) x 13MIN(H)	mm
Activity Display Area	94.84(W)x9.66(H)	mm
Character Font	5x8 Dots	-
Character Size	4.84(W)x8.06(H)	mm
Character Pitch	6(W)x8.56(H)	mm
Dot Size	0.92(W)x1.1(H)	mm

## 3. ELECTRICAL SPECIFICATIONS

### 3-1 ABSOLUTE MAXIMUM RATINGS (Ta = 25 °C)

Item	Symbol	Min	Max	Unit
Supply Voltage For Logic	Vdd	-0.3	+7.0	V
Supply Voltage For LCD Drive	$V_{LCD}$	VDD-10.0	VDD+0.3	V
Input Voltage	Vin	-0.3	VDD+0.3	V
Operating Temp.	Тор	-20	+70	°C
Storage Temp.	Tst	-30	+80	°C

<sup>\*.</sup> NOTE: The response time will be extremely slow when the operating temperature is around -10 $^{\circ}$ C, and the back ground will become darker at high temperature operating.

### **3-2 ELECTRICAL CHARACTERISTICS**

It	ltem		Test Condition	Min.	Тур.	Max.	Unit
Logic supply Voltage		$V_{\scriptscriptstyle DD}$ – Vss		4.5	5	5.5	V
LCD Drive		$V_{\mathrm{OP}} = V_{DD} - V0$		4.35	4.55	4.75	V
	"H" Level (Except OSC1)	V <sub>IH1</sub>		$0.7V_{DD}$	-	$V_{\scriptscriptstyle DD}$	V
	"L" Level (Except OSC1)		Ta = 25 °C VDD=5V±5%	-0.3	-	0.55	V
Input Voltage	"H" Level (OSC1)	V <sub>IH2</sub>	VDD 01 = 070	$0.7V_{DD}$	-	$V_{\scriptscriptstyle DD}$	V
	"L" Level (OSC1)	V <sub>IL2</sub>		-0.2	-	$0.2V_{DD}$	V
Frame F	requency	f <sub>FLM</sub>		-	75	-	Hz
Current C	onsumption	I <sub>DD</sub>		-	1.98	-	mA

### 3-3BACKLIGHT

### 3-3-1. Absolute Maximum Ratings

Item	Symbol	Condition	min	Тур	Max	Unit
Forward Current	IF	Ta = 25 °C	-	-	20	mA
Power Dissipation	PD	1a = 25 C	-	-	75	mW
ReverseCurrent	IR	VR=5.0V/LED	ı	1	15	uA

### 3-3-2. Electrical-optical Characteristics

Item	Symbol	Condition min		nin Typ		Max		Unit	
Forward Current	IF		-		12		12 15		mA
Average Luminous Intensity	lv	Vf=5.0V Ta = 25 °C	180		280		-		cd/m <sup>2</sup>
Colourcoordonate	Colourcoordonato -		Х	Υ	Х	Υ	Х	Υ	
Colourcoordonate	-		0.25	0.25	0.28	0.28	0.32	0.32	-
BackLight Half life Time	-	IF=12mA Ta=25°C	30000			-	,	_	Hours

The brightness is measured without LCD panel

For operation above 25 °C,The lfm&Pd must be derated, the current derating is -0.36mA/°C for DC drive and -0.86mA/°C for Pulse drive, the Power dissipation is -0.75mW/°C.The product working current must not more than the 60% of the lfm or lfp according to the working temperature.

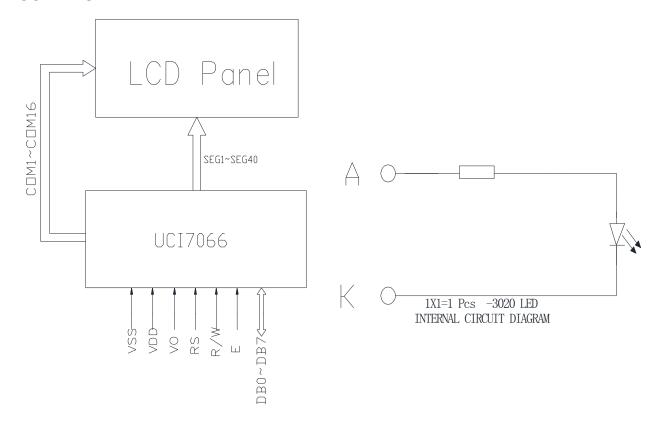
Backlight lifetime means luminance value larger than half of the original after 20000 hours' continuous working.

# 4. TERMINAL FUNCTIONS AND BLOCK DIAGRAM

### **4-1INTERFACE PIN FUNCTION DESCRIPTION**

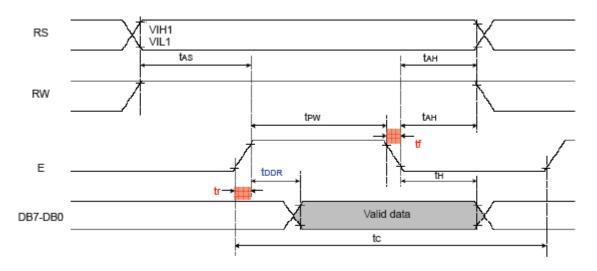
PIN NO.	SYMBOL	FUNCTIONS
1	VSS	Ground
2	VDD	Supply voltage for logical circuit
3	V0	Supply voltage for LCD driving
4	RS	A signal for selecting registers.  1: Data Register (for read and write)  0: Instruction Register (for write)
5	R/W	A signal for selecting read or write actions.1: Read, 0: Write.
6	E	A enable signal for reading or writing data.
7-14	DB0~DB7	8 Bit Data Bus
15	K	Backlight(-)
16	Α	Backlight(+5V)

## **4-2BLOCK DIAGRAM**



# **5. TIMING CHARACTERISTICS**

## 5-1 Reading Data from UCI7066 to MPU

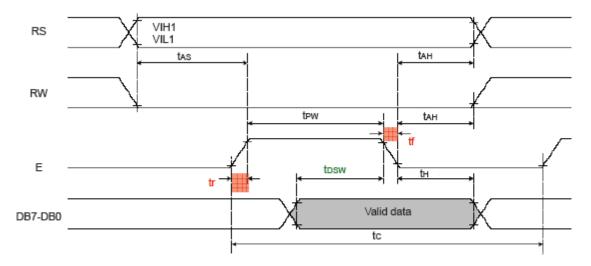


(6800 Read data from UCi7066c)

T<sub>A</sub> = 25°C, Vcc=4.5V~5V

IA = 25 C, VCC=4.5V~5V								
Symbol	Characteristic	Test Condition	Min.	Тур.	Max.	Unit		
Read Mode (M	PU reads data from UCi7066)							
tc	Enable Cycle Time	Pin E	1200			nS		
tpw	Enable Pulse Width	Pin E	140			nS		
tr, tr	Rising/Falling Time	Pin E			25	nS		
tas	Address Setup Time	Pin: RS, RW, E	0			nS		
tан	Address Hold Time	Pin: RS, RW, E	10			nS		
todr	Data Setup Time	Pin: DB7~DB0			100	nS		
tн	Data Hold Time	Pin: DB7~DB0	10			nS		

## 5-2 Writing Data from MPU to UCI7066



(6800 Write data to UCi7066c)

Ta = 25°C, Vcc=4.5V~5V

Symbol	Characteristic	Test Condition	Min.	Тур.	Max.	Unit
<u> </u>	PU writes data to UCi7066)			7,1		
tc	Enable Cycle Time	Pin E	1200			nS
tpw	Enable Pulse Width	Pin E	140			nS
tr, tr	Rising/Falling Time	Pin E			25	nS
tas	Address Setup Time	Pin: RS, RW, E	0			nS
tан	Address Hold Time	Pin: RS, RW, E	10			nS
tosw	Data Setup Time	Pin: DB7~DB0	40			nS
tн	Data Hold Time	Pin: DB7~DB0	10	-		nS

# **6COMMAND LIST**

### **6-1 Instruction Table**

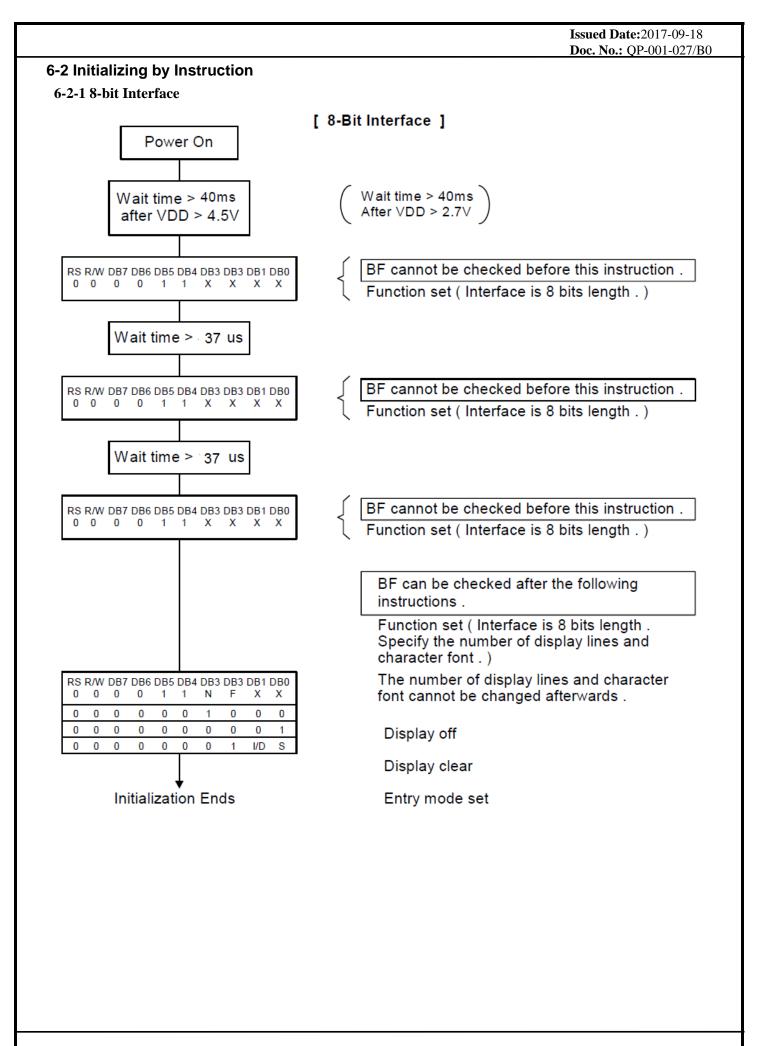
The following is a list of host commands supported by UCi7066

R/S: 0: Control, 1: Data W/R: 0: Write Cycle, 1: Read Cycle D7-D0: -: Don't Care

#	Command	RS	R/W	D7	D6	D5	D4	D3	D2	D1	D0	Action
1	Clear Display	0	0	0	0	0	0	0	0	0	1	Clear the screen
2	Return Home	0	0	0	0	0	0	0	0	1	-	Move cursor to HOME
3	Set Entry Mode	0	0	0	0	0	0	0	1	I/D	S	I/D: Left / Right S: Shift OFF/ON
4	Display ON/OFF	0	0	0	0	0	0	1	D	С	В	D: Display OFF / ON C: Cursor OFF / ON B: Blink OFF / ON
5	Cursor or Display Shift	0	0	0	0	0	1	S/C	R/L	ı	-	S/C: Screen / Cursor R/L Right / Left
6	Set Function	0	0	0	0	1	DL	N	F	ı	1	DL: 4-bit / 8-bit, N: 1-line / 2-line F: 5x8 / 5x11
7	Set CGRAM address	0	0	0	1	AC5	AC4	AC3	AC2	AC1	AC0	
8	Set DDRAM address	0	0	1	AC12	AC11	AC10	AC9	AC8	AC7	AC6	
9	Read Busy Flag and address	0	1	BF	AC19	AC18	AC17	AC16	AC15	AC14	AC13	
10	Write data to RAM	1	0	D7	D6	D5	D4	D3	D2	D1	D0	Write data to RAM
11	Read data from RAM	1	1	D7	D6	D5	D4	D3	D2	D1	D0	Read data from RAM
	For S8/S9 Mode											
12	Status Read	1	1	0	0	0	0	0	0	0	0	Read status
Ľ	Status Neau	0	1	BF	AC19	AC18	AC17	AC16	AC15	AC14	AC13	

#### Note:

Ensure that UCi7066 is not in the BUSY state (BF = 0) before sending an instruction from the MPU to the UCi7066. If an instruction is sent without checking the busy flag, the time between the first instruction and next instruction will take much longer than the instruction time itself.



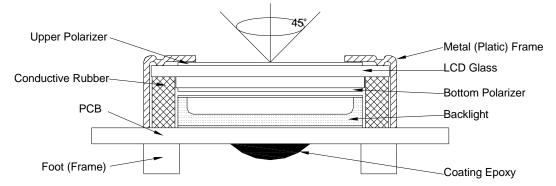
**Issued Date:**2017-09-18 **Doc. No.:** QP-001-027/B0 6-2-2 4-bit Interface [ 4-Bit Interface ] Power On Wait time > 40ms Wait time > 40ms After VDD > 2.7V after VDD > 4.5V RS R/W DB7 DB6 DB5 DB4 BF cannot be checked before this instruction . 0 0 0 Function set (Interface is 8 bits length.) Wait time > 4.1 ms RS R/W DB7 DB6 DB5 DB4 BF cannot be checked before this instruction . 0 0 1 1 Function set (Interface is 8 bits length.) Wait time > 37 us RS R/W DB7 DB6 DB5 DB4 BF cannot be checked before this instruction . 0 0 0 0 1 1 Function set (Interface is 8 bits length.) BF can be checked after the following instructions. RS R/W DB7 DB6 DB5 DB4 0 0 0 1 0 Function set ( Set interface to be 4 bits length) Interface is 8 bits length. 0 0 0 0 0 1 0 0 Ν Χ Function set (Interface is 4 bits length. Χ Specify the number of the display lines 0 0 0 0 0 0 and character font . ) 0 0 0 0 0 1 0 0 0 0 0 The number of display lines and character 0 font cannot be changed afterwards . 0 0 0 0 0 1 0 0 0 0 0 0 Display off 0 1 S 0 0 I/D Display clear Entry mode set Initialization Ends

# 7.CHARACTER GENERATOR ROM

Upper 4 bits Lower	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111
4 bits																
0000																
0001				1												
0010															F	
0011																
0100				4									ŀ	P		
0101															Œ	
0110																
0111			7	P								1				II
1000				8												
1001				9	I							•		ı,		
1010															j	
1011				78	K			Ć			**	77				ħ
1100						¥									4.	
1101															Ł	
1110					H											
1111				P												

## 8. QUALITY SPECIFICATIONS

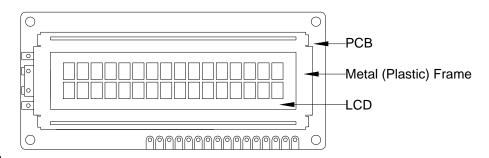
- 8-1. LCM Appearance and Electric inspection Condition
  - 1. Inspection will be done by placing LCM 30cm away from inspector's eyeballs under normal illumination.



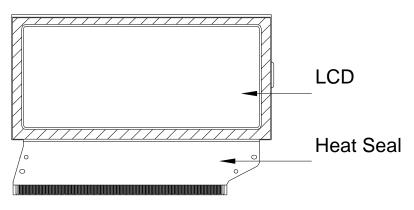
2. View Angle: with in 45° around perpendicular line.

#### 8-2. Definition

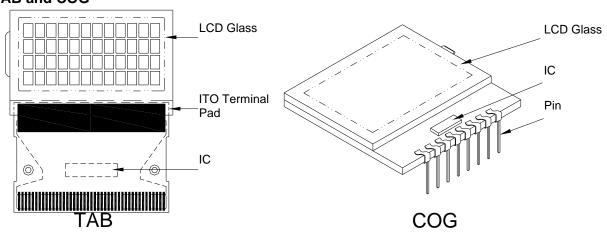
1. COB



2. Heat Seal



3. TAB and COG



## 8-3. Sampling Plan and Acceptance

1. Sampling Plan

MIL - STD - 105E ( || ) ordinary single inspection is used.

2.Acceptance

Major defect: AQL = 0.65%Minor defect: AQL = 1.5%

### 8-4. Criteria

### 1.COB

Defect	Inspection Item	Inspection Standards				
Major	PCB copper flakes peeling off	Any copper flake in viewing Area should be greater than 1.0mm <sup>2</sup>	Reject			
Major	Height of coating epoxy	Exceed the dimension of drawing	Reject			
Major	Void or hole of coating epoxy	Expose bonding wire or IC	Reject			
Major	PCB cutting defect	Exceed the dimension of drawing	Reject			

#### 2.SMT

Defect	Inspection Item	Inspection Standa	ards
Minor	Component marking not readable		Reject
Minor	Component height	Exceed the dimension Of drawing	Reject
Major	Component solder defect (missing, extra, wrong component or wrong orientation		Reject
Minor	Component position shift  component soldering pad  X  D  Y	X < 3/4Z Y > 1/3D	Reject Reject
Minor	Component tilt  component  soldering pad	Y > 1/3D	Reject
Minor	Insufficient solder component PAD	<i>θ</i> ≤ 20°	Reject

### 3. Metal (Plastic) Frame

Defect	Inspection Item	lı lı	nspection Standa	rds			
Major	Crack / breakage	Any	ywhere	Reject			
		W	L	Acceptable of Scratch			
		w<0.1mm	Any	Ignore			
		0.1 <u>&lt;</u> w<0.2mm	L <u>&lt;</u> 5.0mm	2			
Minor	Frame Scratch	0.2 <u>&lt;</u> w<0.3mm	L <u>&lt;</u> 3.0mm	1			
-		w <u>&gt;</u> 0.3mm	Any	0			
		Note: 1. Above criteria applicable to scratch lines with distance greater than 5mm.  2. Scratch on the back side of frame (no visible) can be ignored.					
				Acceptable of Dents / Pricks			
		Φ<	2				
	Frame Dent , Prick	1.0<	1				
Minor	$\Phi = \frac{L + W}{2}$	1.5	$mm {<} \Phi$	0			
	2	/ pricks with dis	e criteria applicable tance greater than rick on the back s ignored	5mm			
Minor	Frame Deformation	Exceed the dimension of drawing					
Minor	Metal Frame Oxidation		Any rust				

### 4. Flexible Film Connector (FFC)

4. Flexible Film Connector (FFC)									
Defect	Inspection Item Inspection Stand			ards					
Minor	Tilted soldering		Within the angle +5°	Acceptable					
Minor	Uneven s	Uneven solder joint /bump		Reject					
			Expose the conductive line	Reject					
Minor	Hole	$\Phi = \frac{L + W}{2}$	Ф> 1.0mm	Reject					
Minor	Position shift  Y  T  T  T  T  T  T  T  T  T  T  T  T		Y > 1/3D	Reject					
IVIII IOI			X > 1/2Z	Reject					

### 5. Screw

Defect Inspection Item		Inspection Standards	
Major	Screw missing/loosen		Reject
Minor	Screw oxidation	Any rust	Reject
Minor	Screw deformation	Difficult to accept screw driver	Reject

### 6. Heatseal \ TCP \ FPC

Defect	Inspection Item	Inspection Standards	
Major	Scratch expose conductive layer		Reject
Minor	HS Hole $\Phi = \frac{L + W}{2}$	⊕> 0.5mm	Reject
Major	Adhesion strength	Less than the specification	Reject
Minor	Position shift	Y > 1/3D	Reject
IVIIIIOI		X > 1/2Z	Reject
Major	Conductive line break		Reject

7. LED Backing Protective Film and Others

Defect	Inspection Item	Inspection Standards	
		Acceptable number of units	
	LED dirty, prick	⊕ <u>&lt;</u> 0.10mm	Ignore
		0.10<⊕ <u>&lt;</u> 0.15mm	2
Minor		0.15<⊕ <u>&lt;</u> 0.2mm	1
		Φ>0.2mm	0
		The distance between any two spots should be ≥ Any spot/dot/void outside of viewing area is accept	
Minor	Protective film tilt	Not fully cover LCD	Reject
Major	COG coating	Not fully cover ITO circuit	Reject

8. Electric Inspection

Defect	Inspection Item	m Inspection Standards							
Major	Short		Reject						
Major	Open		Reject						

9. Inspection Specification of LCD

Defect	ection Specific	ect Item		Inspection Standards					
			W		<0.03		03 <w<0.05< td=""><td></td><td>V&gt;0.05</td></w<0.05<>		V>0.05
		*Glass Scratch	L		<u>&lt;</u> 0.00 L<5	10.0	L<3	<del>_</del>	Any
Minor	Linear Defect	<ul><li>* Polarizer Scratch</li><li>* Fiber and Linear</li></ul>	ACC. NO.				1 F		Reject
		material	Note	L is the length and W is the width of the defect					efect
		* Foreign material	Φ	Φ <u>&lt;</u> 0.1	<u> </u>				⊕>0.2
	Black Spot and	between glass and		3EA / 100mm²	_		1		0
Minor	Polarizer Pricked	and glass  * Polarizer hole or protuberance by external force	Note	Φ is the average diameter of the defect. Distance between two defects >10mm.					
		* Unobvious	Φ	Φ:	<u>&lt;</u> 0.3	0.3<	<⊕ <u>&lt;</u> 0.5	0.	<b>5</b> <⊕
	White Spot	transparant foreign material between	ACC. NO.	3EA /	100mm <sup>2</sup>		1		0
Minor	and Bubble in polarizer	nd Bubble in Iglass and glass or			e average diameter of the defect. e between two defects >10mm.				
	Segment Defect			Ф <u>&lt;</u> 0.10	0.10<⊕≤	0.20	0.20<⊕ <u>&lt;</u> 0.25		Φ>0.25
				3EA / 100mm²	2	2 1			0
Minor		-W-		W is mor	e than 1/2 s	egme	ent width		Reject
		W.	Note	$\Phi = \frac{L + W}{2}$ Distance between two defect is 10mm					
			Φ	Ф <u>&lt;</u> 0.10	0.10<⊕≤	0.20	0.20 0.20<⊕ <u>&lt;</u> 0.25		⊕>0.25
	Protuberant	Protuberant		Glue	Glue W<1/2 Se W<0.2				Ignore
Minor	Segment	$\Phi = (L + W)/2$	ACC. NO.	3EA / 100mm²	2		1		0
			1. Seg	ment					
			В	3 E	3 <u>&lt;</u> 0.4mm	0.4 <e< td=""><td>3<u>&lt;</u>1.0mm</td><td>B&gt;′</td><td>1.0mm</td></e<>	3 <u>&lt;</u> 1.0mm	B>′	1.0mm
	Assembly		B-	A E	3-A<1/2B	B-	A<0.2	B-A	\<0.25
Minor	Mis-alignment		Judge Acceptable		Acceptable Acce		eptable		
			2. Dot	Matrix					
			Deformation>2°				Reject		
Minor	Stain on LCD Panel Surface		or a	similar or	ains can be ne. Otherwi lack spot" al	ise, ju	udged acc		

## 9. RELIABILITY

No	Item	Condition	Quantity	Criteria
1	High Temperature Operating	70°C, 96Hrs	2	GB/T2423.2 -2008
2	Low Temperature Operating	-20°C, 96Hrs	2	GB/T2423.1 -2008
3	High Humidity	50°C, 90%RH, 96Hrs	2	GB/T2423.3 -2006
4	High Temperature Storage	80°C, 96Hrs	2	GB/T2423.2 -2008
5	Low Temperature Storage	-30°C, 96Hrs	2	GB/T2423.1 -2008
6	Thermal Cycling Test	-20°C, 60min~70°C, 60min, 20 cycles.	2	GB/T2423.2 2 -2012
7	Packing vibration	Frequency range:10Hz~50Hz Acceleration of gravity:5G X,Y,Z 30 min for each direction.	2	GB/T5170.1 4 -2009
8	Electrical Static Discharge	Air: $\pm 8$ KV 150pF/330 $\Omega$ 5 times	2	GB/T17626.
	Electrical Static Discharge	Contact: $\pm 4$ KV 150pF/330 $\Omega$ 5 times	2	-2006
9	Drop Test (Packaged)	Height:80 cm,1 corner, 3 edges, 6 surfaces.	2	GB/T2423.8 -1995

Note:1) Above conditions are suitable for our company standard products.

<sup>2)</sup> For restrict products, the test conditions listed as above must be revised.

### 10. HANDLING PRECAUTION

(1) Mounting Method

The panel of the LCD Module consists of two thin glass plates with polarizers which easily getdamaged since the Module is fixed by utilizing fitting holesin the printed circuit board. Extreme care should be taken when handling the LCD Modules.

(2) Caution of LCD handling & cleaning

When cleaning the display surface, use soft cloth with solvent (recommended below) and wipe lightly.

- Isopropyl alcohol
- Ethyl alcohol
- Trichlorotrifloro thane

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface.

Do not use the following solvent:

- Water
- Ketone
- Aromatics

### (3) Caution against static charge

The LCD Module use C-MOS LSI drivers, so we recommend that you connect any unused input terminal to VDD or VSS, do not input any signals before power is turned on. Andground your body, Work/assembly table. Andassembly equipment toprotect against staticelectricity.

### (4) Packaging

- Modules use LCD elements, and must be treated as such. Avoid intense shock and falls from a height.
- To prevent modules from degradation. Do not operate or store them exposed directly to sunshine or high temperature/humidity.

#### (5) Caution for operation

- It is indispensable to drive LCD's within the specified voltage limit since the higher voltage than the limit shorten LCD life. An electrochemical reaction due to direct current causes LCD deterioration, Avoid the use of direct current drive.
- Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD's show dark color in them. However those phenomena do not mean malfunction or out of order with LCD's. Which will come back in the specified operating temperature range.
- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
- A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.

Usage under the relative condition of 40°C, 50%RH or less is required.

### (6) Storage

In the case of storing for a long period of time (for instance.) For years) for the purpose or replacement use, The following ways are recommended.

- Storage in a polyethylene bag with sealed so as not to enter fresh air outside in it, And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light is. Keeping temperature in the specified storage temperature range.
- Storing with no touch on polarizer surface by the anything else. (It is recommended to store them as they have been contained in the inner container at the time of delivery)

#### (7) Safety

- It is recommendable to crash damaged or unnecessary LCD into pieces and wash off liquid crystal by using solvents such as acetone and ethanol. Which should be burned up later.

When any liquid crystal leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water.

### (8) Other

- After the product shipped, any product quality issues must be feedback within three months, otherwise, we will not be responsible for the subsequent or consequential events.

